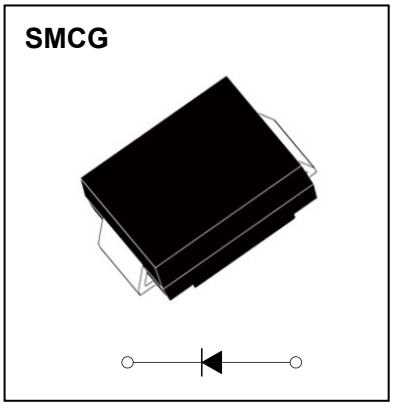
SZCJ Shenzhen Changji Semiconductor Co., LTD.

SMCG Plastic-Encapsulate Diodes

MURS320 THRU MURS360 Super Fast Recovery Rectifier Diodes

Features

- $I_{F(AV)}$ 3A
- V_{RRM} 200V-600V
- High surge current capability
- Polarity: Color band denotes cathode



Applications

- Rectifier

Marking

- MURS3X0

X：From 2 to 6

Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	MURS3			
				20	30	40	60
Repetitive Peak Reverse Voltage	V_{RRM}	V		200	300	400	600
Maximum RMS Voltage	V_{RMS}	V		140	210	280	420
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave Resistance load	3.0			
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	100			
Operation Junction and Storage Temperature Range	T_J,T_{STG}	℃		-55 ~ +150			

Electrical Characteristics (Ta=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		MURS3			
					20	30	40	60
Peak Forward Voltage	V_F	V	I_F=3.0A		0.875	1.25		
Reverse recovery time	t_{rr}	ns	I_F=0.5A,I_R=1.0A, Irr=0.25A		25	50		
Peak Reverse Current	I_{RRM1}	μA	V_{RM}=V_{RRM}	Ta=25 ℃	5			
	I_{RRM2}			Ta=125 ℃	100			
Thermal Resistance(Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		102			
	$R_{\theta J-L}$		Between junction and terminal		4			
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		49	27		

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on 1" x 1"(25.4mm x 25.4mm) FR4 PCB, double sided copper, with minimum pad layout

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

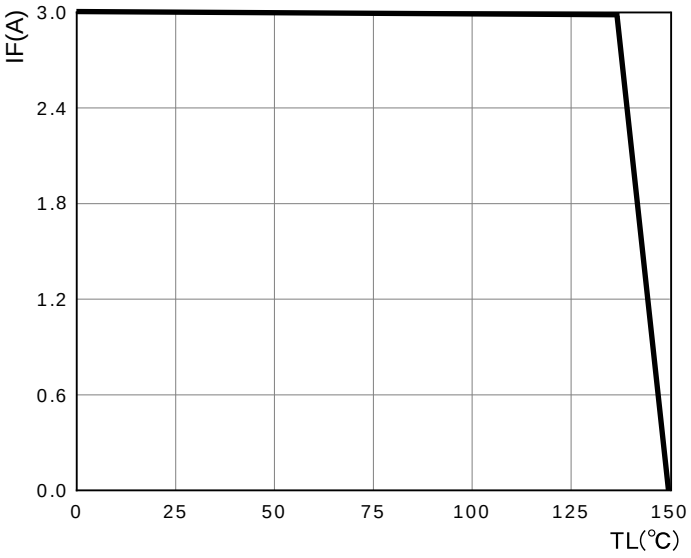
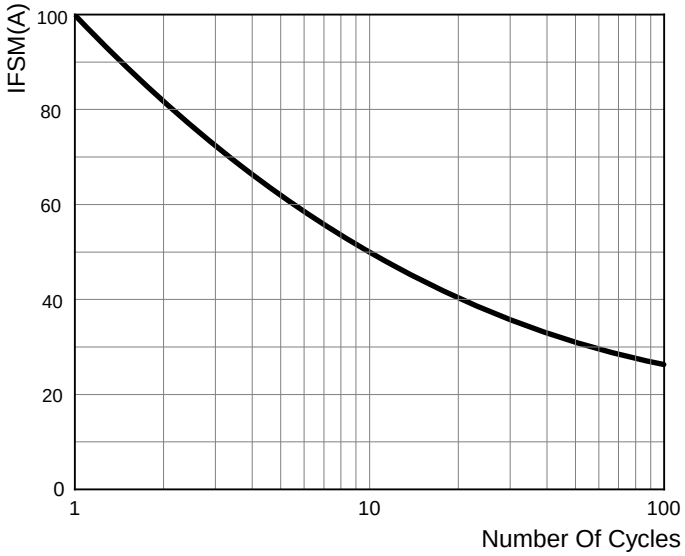
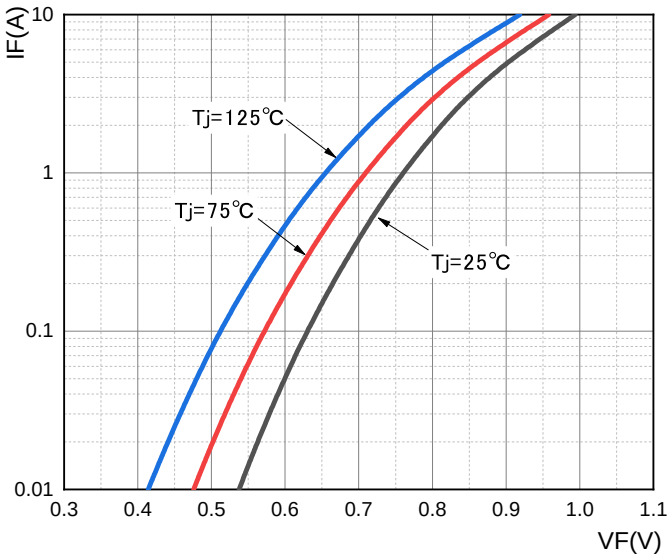


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



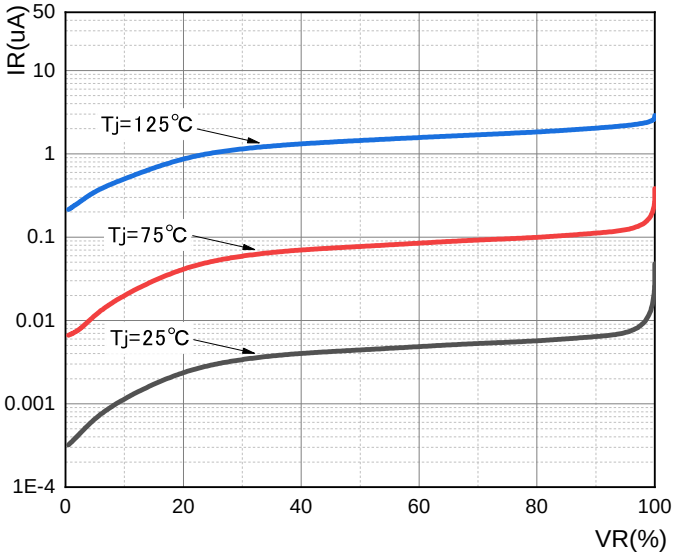
MURS320

FIG.3 : TYPICAL FORWARD CHARACTERISTICS



MURS320

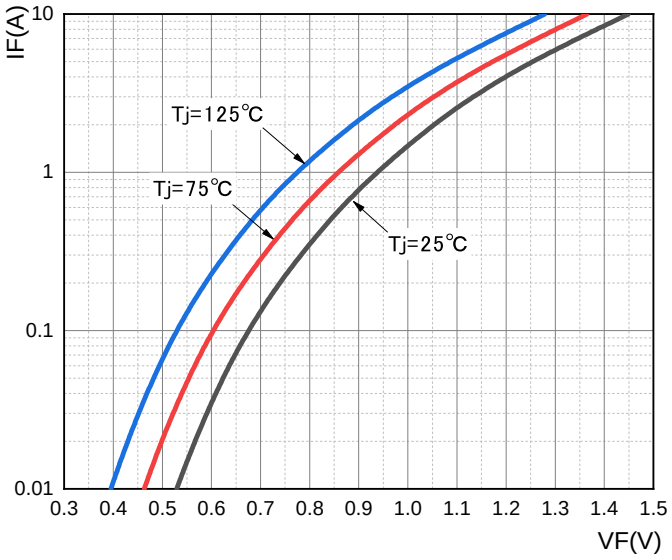
FIG.4 TYPCAL REVERSE CHARACTERISTICS



Typical Characteristics

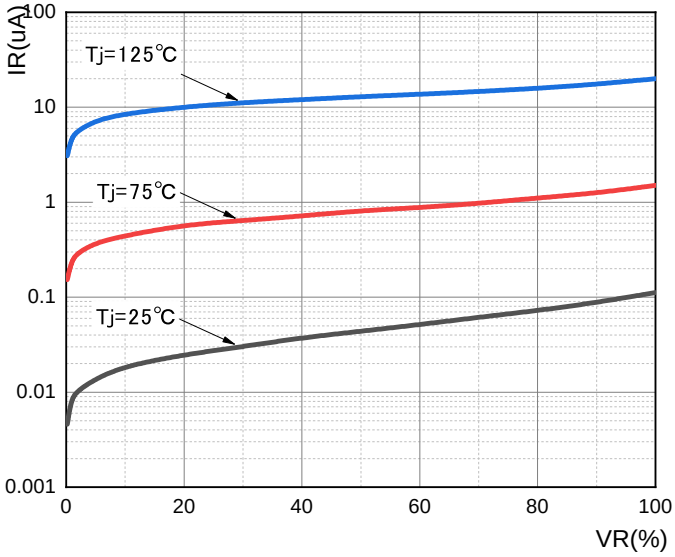
MURS330-MURS360

FIG.5 : TYPICAL FORWARD CHARACTERISTICS

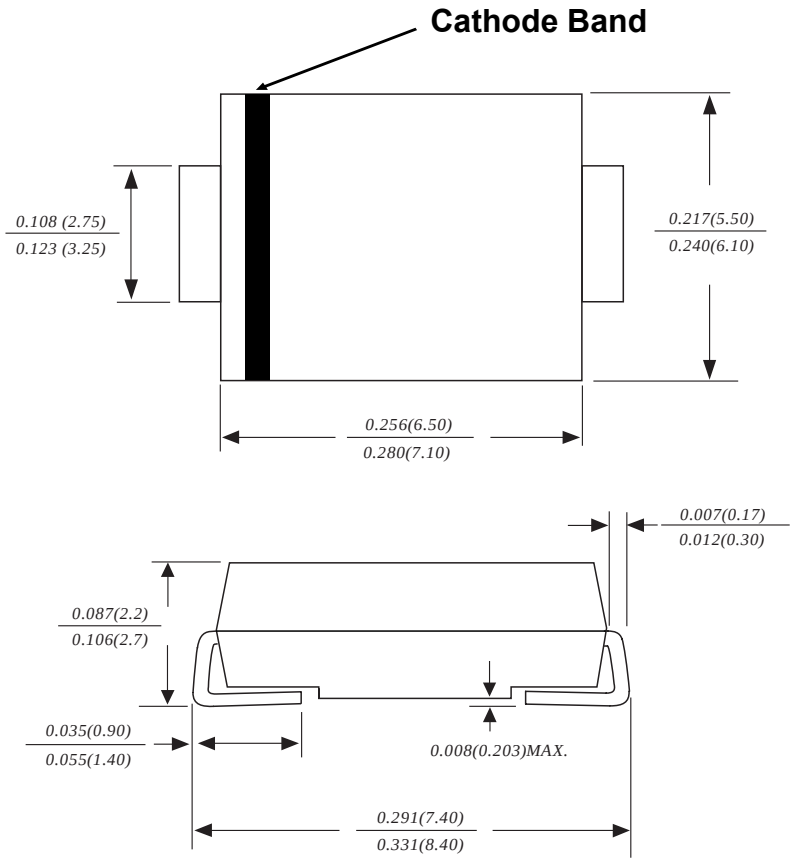


MURS330-MURS360

FIG.6 TYPCAL REVERSE CHARACTERISTICS

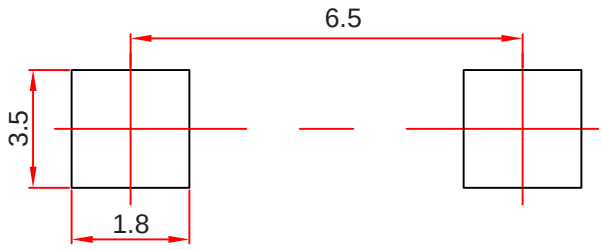


SMCG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMCG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

SZCJ reserves the right to make modifications,enha nts,improvements,corrections or other es without further notice to any product herein.SZCJ does not assume any liability arising out of the application or use of any product described .

Reel Taping Specifications For Surface Mount Devices- SMCG

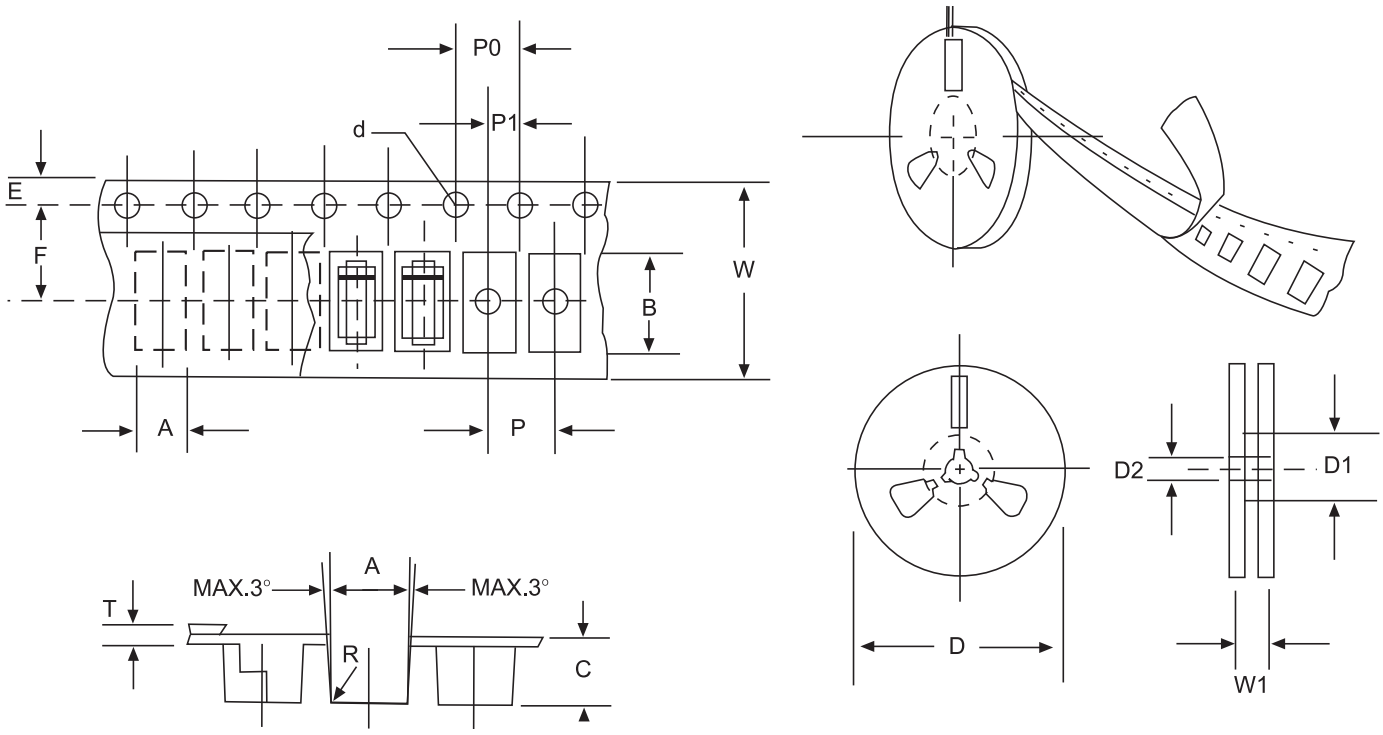


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMCG mm(inch)
Carrier width	A	6.05±0.1(0.238±0.004)
Carrier length	B	8.31±0.1(0.327±0.004)
Carrier depth	C	2.70±0.1(0.106±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0(2.95±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	7.65±0.05(0.301±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.3±0.1(0.012±0.004)
Tape width	W	16.0±0.2(0.630±0.008)
Reel width	W1	24.0±2.0(0.945±0.079)

NOTE:Devices are packed in accordance with EIA standard RS-481-A and specification given above.